CLAIMS:

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- 3 1. A data storage device comprising:
- 4 an array of resistive memory cells having rows and columns;
- 5 a set of diodes electrically connected in series to a plurality of resistive 6 memory cells in the array;
- a plurality of word lines extending along the rows of the array; 7
- 8 a plurality of bit lines extending along the columns of the array;
- a first selected resistive memory cell in the array, wherein the first selected 10 resistive memory cell is positioned between a first word line in the plurality of word lines and a first bit line in the plurality of bit lines; and
 - a circuit electrically connected to the array and capable of applying a first voltage to the first word line, a second voltage to the first bit line, and a third voltage to at least one of a second word line in the plurality of word lines and a second bit line in the plurality of bit lines.
- 16 2. The device of claim 1, wherein the array of resistive memory cells comprises a 17 magnetic random access memory (MRAM) cell.
- 18 The device of claim 2, wherein the MRAM memory cell comprises a tunnel 3. 19 junction.
- 20 4. The device of claim 1, wherein the set of diodes comprises thin-film diodes.
- 21 5. The device of claim 1, further comprising a second resistive memory cell in the
- array, wherein the second resistive memory cell is stacked upon the first selected 22
- 23 resistive memory cell.
- 24 6. The device of claim 1, wherein the circuit is capable of writing to the first selected
- 25 resistive memory cell by applying sufficient energy to the first word line and the
- 26 first bit line to transform the first selected resistive memory cell from a first
- 27 resistance state to a second resistance state.
- 28 7. The device of claim 1, wherein the circuit is capable of sensing a current flowing
- 29 through the first selected resistive memory cell.
- 30 8. The device of claim 1, wherein values of the first voltage and the third voltage are 31 substantially equal.
- 9. 32 The device of claim 1, wherein the circuit is capable of grounding at least one of 33 the second word line and the second bit line.

10.	A method of sensing a resistance state of a first selected resistive memory cell in a
	data storage device that includes an array of resistive memory cells, a plurality of
	word lines extending along rows of the array, a plurality of bit lines extending
	along columns of the array, the first selected resistive memory cell in the array,
	wherein the first selected resistive memory cell is positioned between a first word
	line in the plurality of word lines and a first bit line in the plurality of bit lines, and
	a circuit electrically connected to the array, the method comprising:

providing a set of diodes electrically connected to a plurality of resistive memory cells in the array;

applying a first voltage to the first word line, a second voltage to the first bit line, and a third voltage to at least one of a second word line in the plurality of word lines and a second bit line in the plurality of bit lines; and

- sensing a signal current flowing through the first selected resistive memory cell.
- 15 11. The method of claim 10, further comprising determining a particular resistance 16 state of the first selected resistive memory cell by comparing the signal current to 17 a reference current value.
- 18 12. The method of claim 10, wherein the providing step comprises providing a set of thin-film diodes.
- The method of claim 10, wherein the sensing step comprises sensing the signal current flowing through a magnetic random access memory (MRAM) cell.
- The method of claim 10, wherein the applying step comprises applying the third voltage to a plurality of word lines other than the first word line.
- The method of claim 10, wherein the applying step comprises applying the third voltage to a plurality of bit lines other than the first bit line.
- The method of claim 10, further comprising sensing a signal current flowing
 through a second resistive memory cell positioned in a stacked configuration
 relative to the first selected resistive memory cell.
- The method of claim 10, wherein the applying step comprises applying the first voltage and the third voltage having substantially equal values.
- The method of claim 10, wherein the applying step comprises grounding at least one of the second word line and the second bit line.
- The method of claim 10, further comprising writing data to the first selected resistive memory cell by selecting the first voltage and the second voltage such

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- that the first voltage and the second voltage change the first selected memory cell from a first resistance state to a second resistance state.
- The method of claim 10, wherein the providing step comprises providing that the set of diodes be electrically connected in series with the plurality of resistive memory cells.